

January 7, 1998

CHARACTERISTICS (@ 25°C unless otherwise specified)

	Symbol	3PM2	3PM4	3PM6	3PM8	3PM0	Unit	
Average forward current (sine wave) - max. pcb mounted; T _A = 55°C - max. L = 3/8"; T _L = 55°C	I _{F(AV)}	←————— 1.5 —————→						A
I ² t for fusing (t = 8.3mS) max.	I _{F(AV)}	←————— 3.5 —————→						A
	I ² t	←————— 31 —————→						A ² S
Forward voltage drop max. @ I _F = 3.0A, T _j = 25°C	V _F	←————— 1.15 —————→						V
Reverse current max. @ V _{RWM} , T _j = 25°C	I _R	←————— 1.0 —————→						μA
@ V _{RWM} , T _j = 100°C	I _R	←————— 10 —————→						μA
Reverse recovery time typ. 0.5A I _F to 1.0A I _R . Recovers to 0.25A I _{RR} .	t _{rr}	←————— 2.5 —————→						μS
Junction capacitance typ. @ V _R = 5V, f = 1MHz	C _j	←————— 33 —————→						ρF
Thermal resistance - junction to lead Lead length = 0.375"	R _{θJL}	←————— 26 —————→						°C/W
Lead length = 0"	R _{θJL}	←————— 12 —————→						°C/W
Thermal resistance - junction to amb. on 0.06" thick pcb. 1oz copper.	R _{θJA}	←————— 75 —————→						°C/W

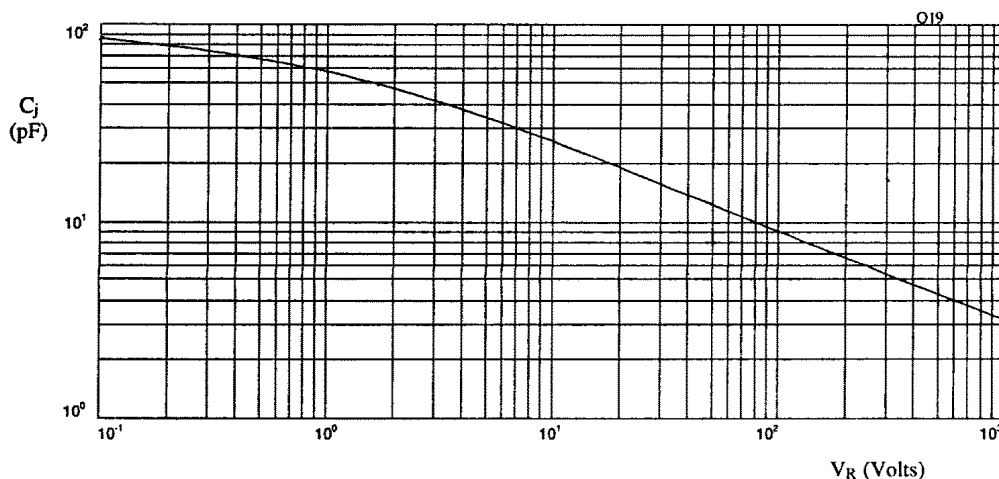


Fig 1. Typical junction capacitance as a function of reverse voltage at f = 1MHz.

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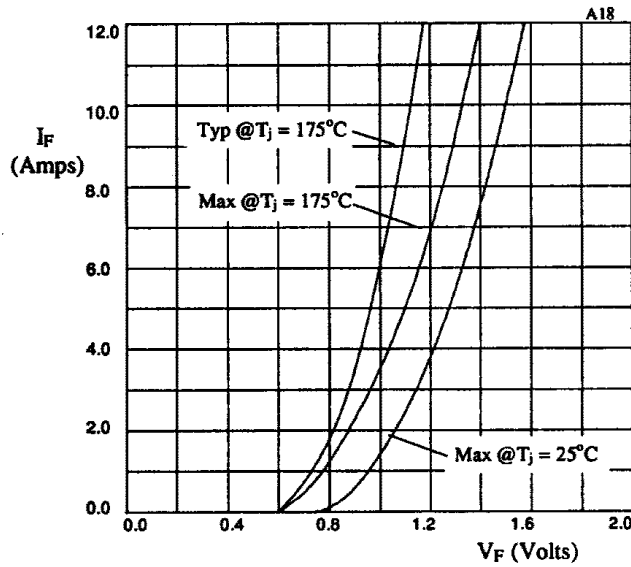


Fig 2. Forward voltage drop as a function of forward current.

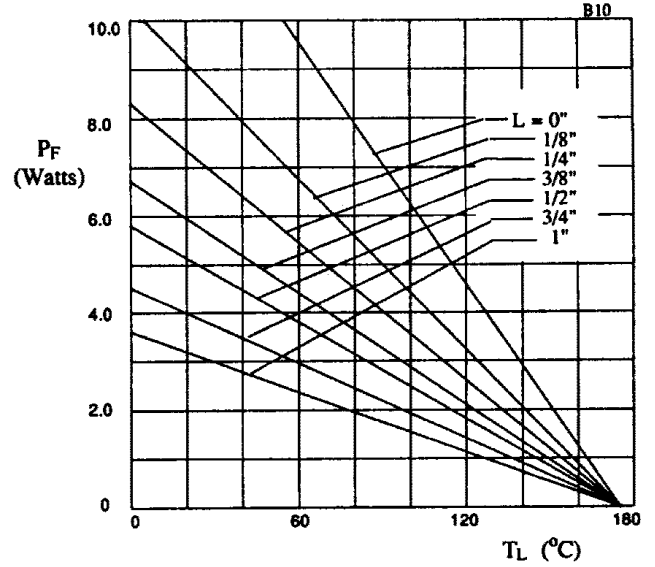


Fig 3. Maximum power versus lead temperature.

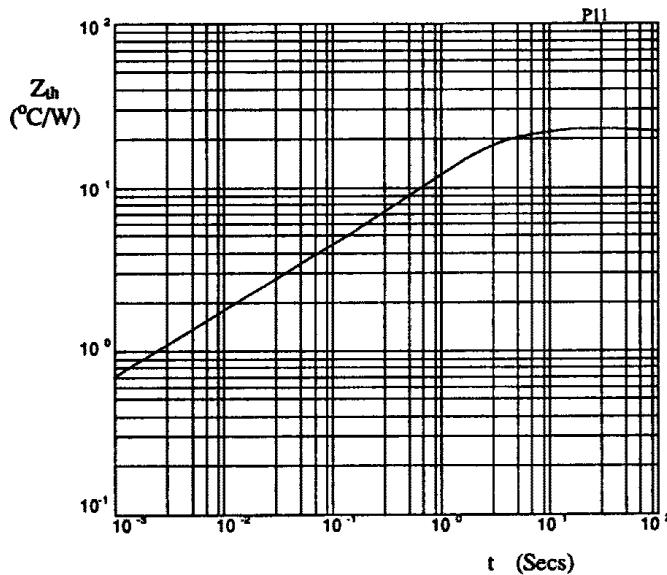


Fig 4. Transient thermal impedance characteristic.

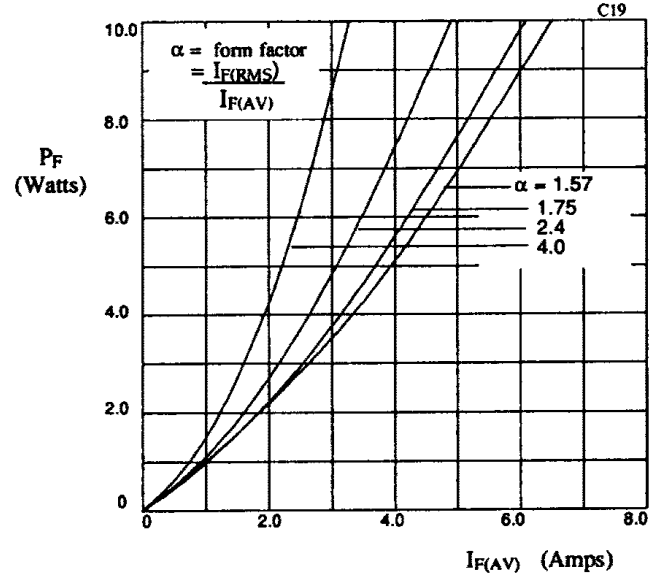


Fig 5. Forward power dissipation as a function of forward current, for sinusoidal operation.